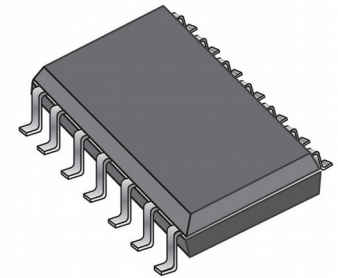
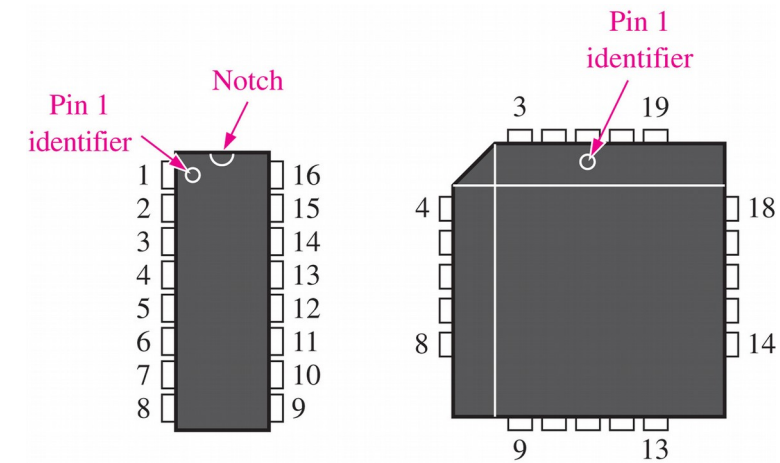


(a) Dual in-line package (DIP)

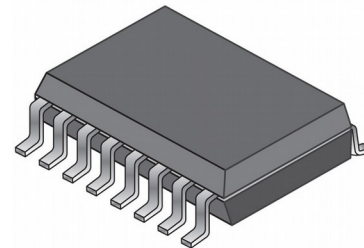


(b) Small-outline IC (SOIC)

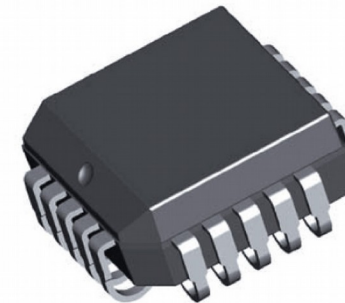


(a) DIP or SSOP

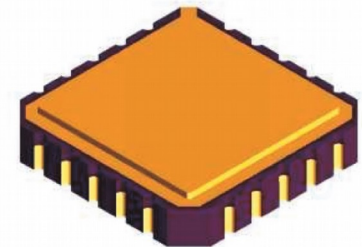
(b) PLCC or LCC



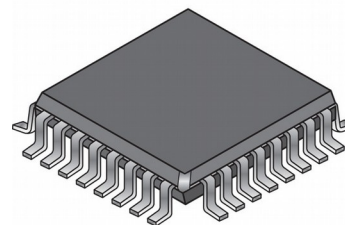
(a) SSOP (153 × 193 mils)



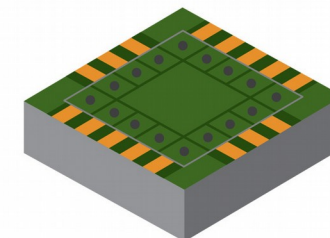
(b) PLCC (350 × 350 mils)



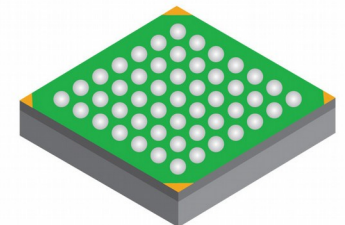
(c) LCC (350 × 350 mils)



(d) LQFP (7 × 7 mm)



(e) Laminate CSP bottom view
(3.5 × 3.5 mm)



(f) FBGA bottom view
(4 × 4 mm)